

EUROPEAN PATENT OFFICE
U.S. PATENT AND TRADEMARK OFFICE

CPC NOTICE OF CHANGES 1919

DATE: AUGUST 1, 2026

PROJECT DP12867

The following classification changes will be effected by this Notice of Changes:

<u>Action</u>	<u>Subclass</u>	<u>Group(s)</u>
DEFINITIONS:		
Definitions New:	H05K	3/3465, 3/3494
Definitions Modified:	H05K	3/00, 3/321, 3/34

No other subclasses/groups are impacted by this Notice of Changes.

This Notice of Changes includes the following [Check the ones included]:

1. CLASSIFICATION SCHEME CHANGES

- A. New, Modified or Deleted Group(s)
- B. New, Modified or Deleted Warning(s)
- C. New, Modified or Deleted Note(s)
- D. New, Modified or Deleted Guidance Heading(s)

2. DEFINITIONS

- A. New or Modified Definitions (Full definition template)
- B. Modified or Deleted Definitions (Definitions Quick Fix)

3. REVISION CONCORDANCE LIST (RCL)

4. CHANGES TO THE CPC-TO-IPC CONCORDANCE LIST (CICL)

5. CHANGES TO THE CROSS-REFERENCE LIST (CRL)

2. A. DEFINITIONS (new)

H05K 3/3465

Definition statement

This place covers:

Processes and apparatus specially adapted for the application of solder for electrically connecting electric components or wires to printed circuits.

Relationships with other classification places

Screen printers for the application of solder may also be classified in group [B41F 15/08](#).

H05K 3/3494

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

Heating appliances for soldering or unsoldering, not specially adapted for particular methods

B23K 3/04

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2. A. DEFINITIONS (modified)

H05K3/00

Replace: The existing Definition statement text with the following updated text.

Definition statement

This place covers:

General processing of printed circuit boards [PCBs]:

- processing of insulating substrates or layers for PCBs or processing of conductive layers for PCBs;
- forming printed elements for providing electric connection to or between printed circuits;
- manufacturing multilayer printed circuits;
- manufacturing metal core printed circuits;
- secondary treatment of PCBs;
- mounting or printing electric components on PCBs;
- assembling PCBs with other PCBs.

H05K 3/00 covers mainly manufacturing (apparatuses and process) of printed circuits. However, certain sub-groups of H05K 3/00 also cover the respective structural aspects (e.g. H05K 3/303, H05K 3/306) and materials (e.g. H05K 3/386).

Replace: The existing Relationships text with the following updated text.

Relationships with other classification places

There is no clear boundary between the field of printed circuit boards and other more specific fields, e.g. inductors (H01F), antennas (H01Q), waveguides (H01P), chip cards (G06K 19/07), thin film and thick film circuits (H10D 84/201, H10D 86/80), other packaging levels (semiconductor packages H10W 90/00 and H10W 99/00), connectors (H01R) and various electronic components. The materials and methods, e.g. deposition, patterning or connection, used for manufacture of printed circuit boards have their general fields.

References

Replace: The existing Informative references table with the following updated table.

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Informative references

Attention is drawn to the following places, which may be of interest for search:

Apparatus specially adapted for manufacturing assemblages of electric components	H05K 13/00
Working of metal by electro-erosion in general	B23H
Machining by laser in general	B23K 26/00
Laminates in general	B32B
Forme preparation for stencil printing or silk-screen printing	B41C 1/14
Printing apparatus in general	B41F
Printing techniques in general	B41M
Stencils, stencil materials or carriers therefor	B41N 1/24
Covering metals by metal spraying	C23C 4/00
Coating by vacuum evaporation, e.g. sputtering	C23C 14/00
Covering materials by cathodic sputtering	C23C 14/34
Chemical coating of a substrate by decomposition in general	C23C 18/00
Electroless plating in general	C23C 18/16
Non-mechanical removal of metallic material from surfaces	C23F
Local etching in general	C23F 1/02
Apparatus for etching in general	C23F 1/08
Etchants in general	C23F 1/10 - C23F 1/46
Electroplating in general	C25D

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Photomechanical production of textured or patterned surfaces, materials or originals therefor, apparatus specially adapted therefor, in general	G03F
Etching masks applied by electrographic, electrophotographic or magnetographic methods in general	G03G
Electron-beam or ion-beam tubes for localised treatment	H01J 37/30
Discharge devices for covering materials by cathodic sputtering	H01J 37/34
Connectors for printed circuits	H01R 12/00
Processes or apparatus adapted for the manufacture or treatment of semiconductor or solid-state devices or of parts thereof	H10P 95/00
Generic processes or apparatus for the manufacture or treatment of devices covered by class H10	H10P

Delete: The entire Special rules section.

H05K3/321

References

Replace: The existing Informative references table with the following updated table.

Informative references

Attention is drawn to the following places, which may be of interest for search:

Connections using electrically conductive adhesives in general	H01R 4/04
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H05K3/34

References

Replace: The existing Informative references table with the following updated table.

Informative references

Attention is drawn to the following places, which may be of interest for search:

Soldering, e.g. brazing, or unsoldering	B23K 1/00
Tools, devices or special appurtenances for soldering, e.g. brazing, or unsoldering, not specially adapted for particular methods	B23K 3/00